

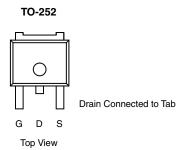
P-Channel 40 V (D-S) 175 °C MOSFET

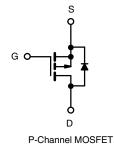
PRODUCT SUMMARY					
V _{DS} (V)	- 40				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.0068				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.0130				
I _D (A)	- 90				
Configuration	Single				

FEATURES

- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- \bullet 100%R $_{\rm g}$ and UIS Tested







ABSOLUTE MAXIMUM RATING	GS (T _C = 25 °C, unles	s otherwise noted	<u>d)</u>		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V_{DS}	- 40	V		
Gate-Source Voltage	V_{GS}	± 20	V		
Continuous Drain Current ^a	T _C = 25 °C	1	- 90		
	T _C = 125 °C	l _D	- 52		
Continuous Source Current (Diode Conduc	I _S	- 100	Α		
Pulsed Drain Current ^b	I _{DM}	-280			
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	- 50		
Single Pulse Avalanche Energy	L = 0.1 MH	E _{AS}	125	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	P _D	136	W	
	T _C = 125 °C		45	VV	
Operating Junction and Storage Temperation	T _J , T _{stg}	- 55 to + 175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount ^c	R_{thJA}	50	°C/W	
Junction-to-Case (Drain)		R_{thJC}	1.1	C/ VV	

Notes

- a. Package limited.
- b. Pulse test; pulse width $\leq 300~\mu s,\,duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.

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SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 40	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = -250 \mu A$		-	- 2.5	V	
Gate-Source Leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = - 40 V	ı	-	- 1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = -40 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	-	- 50	μΑ	
		$V_{GS} = 0 V$	V _{DS} = - 40 V, T _J = 175 °C	-	-	- 150		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 10 V	$V_{DS} \le -5 V$	- 50	-	ı	Α	
		V _{GS} = - 10 V	I _D = - 17 A	-	0.0068	-	Ω	
Dwain Course On State Decistance		V _{GS} = - 10 V	I _D = - 50 A, T _J = 125 °C	-	0.0147	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 50 A, T _J = 175 °C	-	0.0178	-		
		V _{GS} = - 4.5 V	I _D = - 14 A	-	0.0130	-		
Forward Transconductanceb	9 _{fs}	V _{DS} =	- 15 V, I _D = - 17 A	-	46	-	S	
Dynamic ^b							•	
Input Capacitance	C _{iss}		GS = 0 V V _{DS} = - 20 V, f = 1 MHz	-	5339	6675	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$		-	852	1065		
Reverse Transfer Capacitance	C _{rss}			-	681	855		
Total Gate Charge ^c	Qg			-	103	155		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = - 10 V	$V_{DS} = -20 \text{ V}, I_{D} = -50 \text{ A}$	-	15	-	nC	
Gate-Drain Charge ^c	Q _{gd}			-	21	-		
Gate Resistance	R _g	f = 1 MHz		1.4	2.8	4.2	Ω	
Turn-On Delay Time ^c	t _{d(on)}	$V_{DD} = \text{- }20 \text{ V}, \text{ R}_{L} = \text{0.4 }\Omega$ $I_{D} \cong \text{- }50 \text{ A}, \text{ V}_{GEN} = \text{- }10 \text{ V}, \text{ R}_{g} = \text{1 }\Omega$		-	13	20		
Rise Time ^c	t _r			-	15	23	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	61	92		
Fall Time ^c	t _f			-	19	29		
Source-Drain Diode Ratings and Characteristics ^b								
Pulsed Current ^a	I _{SM}			-	-	- 160	Α	
Forward Voltage	V _{SD}	I _F = - 50 A, V _{GS} = 0 V		-	- 0.95	- 1.5	V	

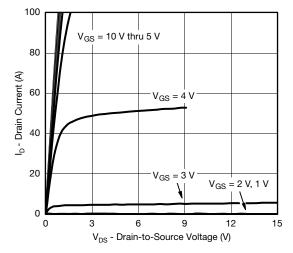
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

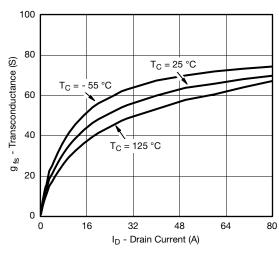
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



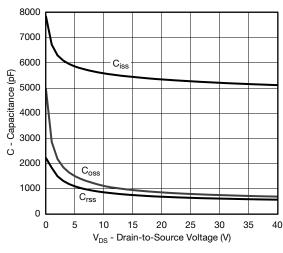
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



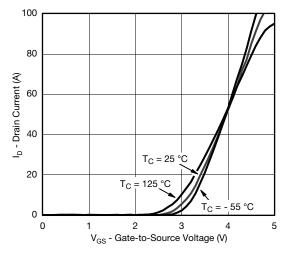
Output Characteristics



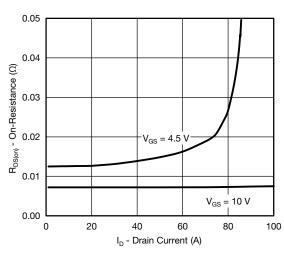
Transconductance



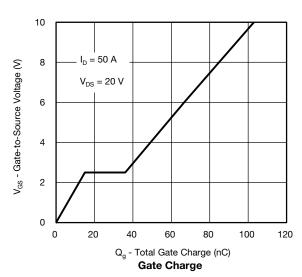
Capacitance



Transfer Characteristics

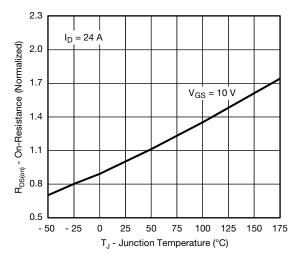


On-Resistance vs. Drain Current

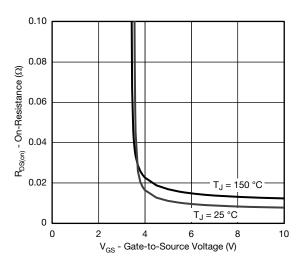




TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

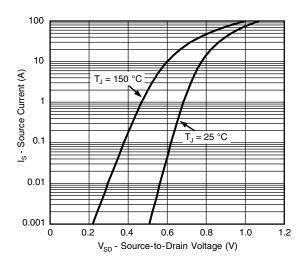


On-Resistance vs. Junction Temperature

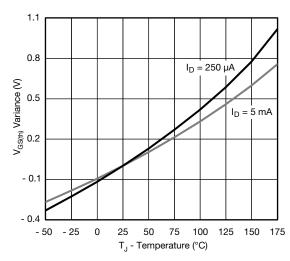


On-Resistance vs. Gate-to-Source Voltage

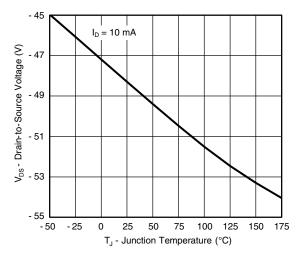
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Source Drain Diode Forward Voltage



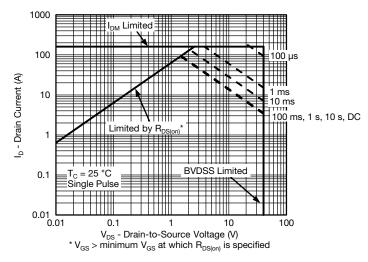
Threshold Voltage



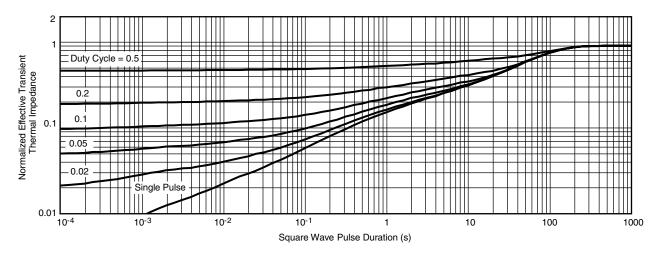
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



Safe Operating Area



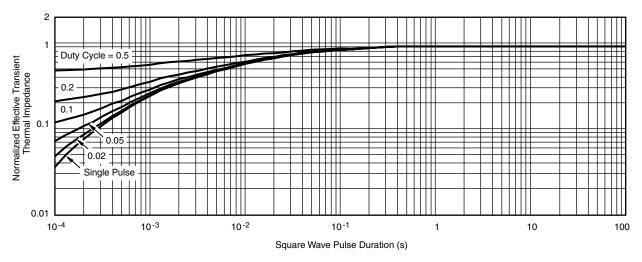
Normalized Thermal Transient Impedance, Junction-to-Ambient

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THERMAL RATINGS ($T_A = 25 \, ^{\circ}\text{C}$, unless otherwise noted)



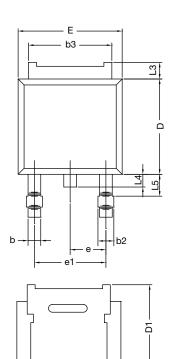
Normalized Thermal Transient Impedance, Junction-to-Case

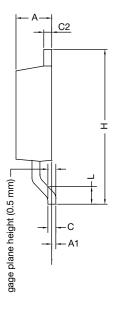
Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



TO-252AA Case Outline





	MILLIMETERS INCHES			HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090	BSC	
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T13-0592-Rev. A, 02-Sep-13					

DWG: 6019

Note

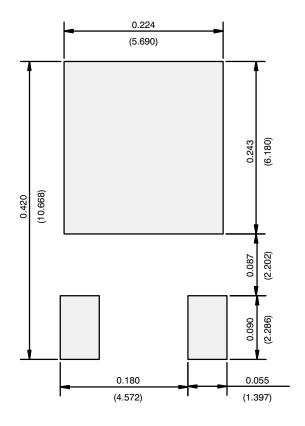
• Dimension L3 is for reference only.

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RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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